SunLED
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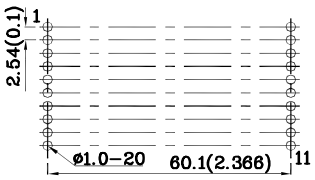
Part Number: XAUR60C

56.8mm (2.3 ") 16 SEGMENT SINGLE DIGIT ALPHANUMERIC DISPLAY

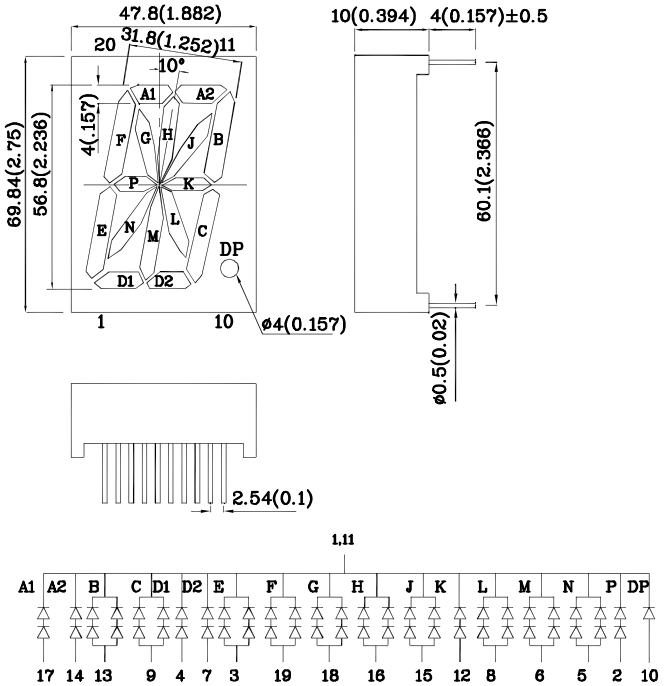
Features

- Low power consumption
- Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant

RECOMMENDED PCB LAYOUT

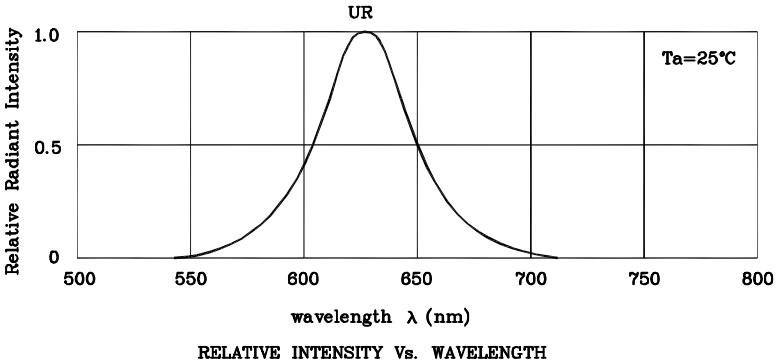


Package Schematics



Notes:
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.
2. Specifications are subject to change without notice.

Part Number	Emitting Color	Emitting Material	Luminous Intensity (I_F=10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XAUR60C	Red	GaAsP/GaP	3600	8490	627	Common Cathode, Rt. Hand Decimal.



RELATIVE INTENSITY Vs. WAVELENGTH

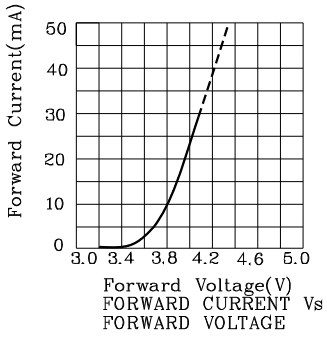
Part Number: XAUR60C

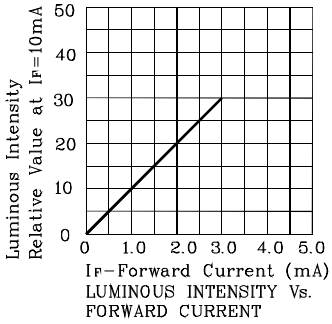
56.8mm (2.3 ") 16 SEGMENT SINGLE DIGIT ALPHANUMERIC DISPLAY

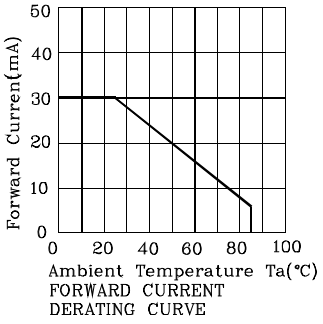
Absolute maximum ratings (TA=25°C)			**UR (GaAsP/GaP)**	**Unit**
Reverse Voltage	A1,A2,D1, D2,P,K	VR	5	V
	B,C,E,F,G, H,J,L,M,N		5	
	DP		5	
Forward Current	A1,A2,D1, D2,P,K	IF	30	mA
	B,C,E,F,G, H,J,L,M,N		60	
	DP		30	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	A1,A2,D1, D2,P,K	iFS	160	mA
	B,C,E,F,G, H,J,L,M,N		320	
	DP		160	
Power Dissipation	A1,A2,D1, D2,P,K	PD	150	mW
	B,C,E,F,G, H,J,L,M,N		300	
	DP		75	
Operating Temperature		TA	-40 ~ +85	°C
Storage Temperature		Tstg	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]		260°C For 3~5 Seconds		

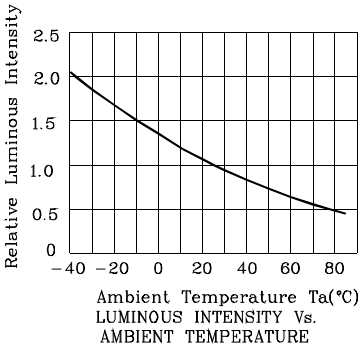
Operating Characteristics (TA=25°C)			**UR (GaAsP/GaP)**	**Unit**
Forward Voltage (Typ.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	3.8	V
	B,C,E,F,G,H, J,L,M,N			
	DP		1.9	
Forward Voltage (Max.) (IF=10mA)	A1,A2,D1,D2, P,K	VF	5	V
	B,C,E,F,G,H, J,L,M,N			
	DP		2.5	
Reverse Current (Max.) (VR=5V)	A1,A2,D1,D2, P,K	IR	10	uA
Reverse Current (Max.) (VR=5V)	B,C,E,F,G,H, J,L,M,N		20	
Reverse Current (Max.) (VR=5V)	DP		10	
Wavelength of Peak Emission (Typ.) (IF=10mA)		λP	627	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)		λD	625	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=10mA)		Δλ	45	nm
Capacitance (Typ.) (VF=0V, f=1MHz)		C	15	pF

❖ UR

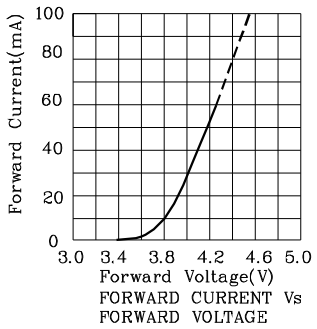


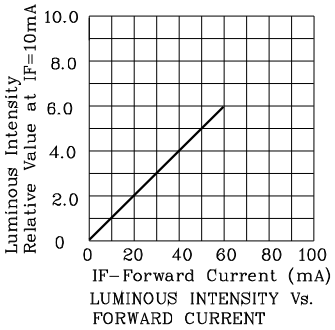


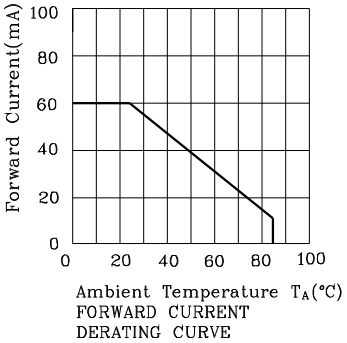


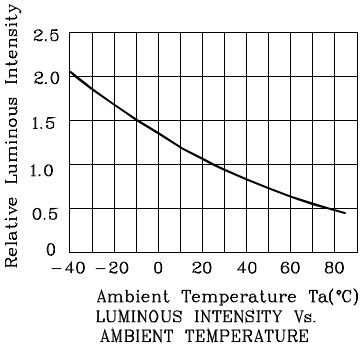


Note:the curves are on the segment a1,a2,d1,d2,p,k.

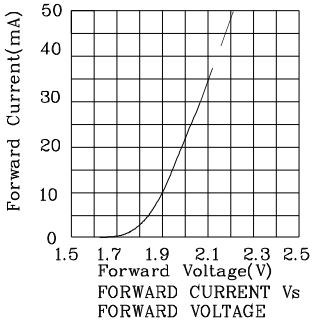


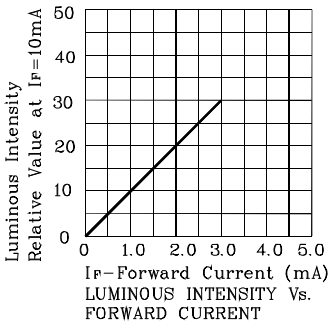


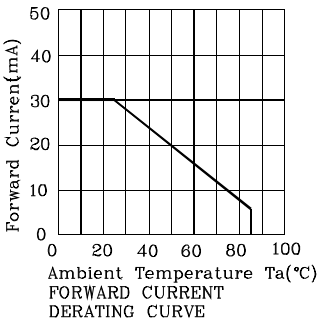


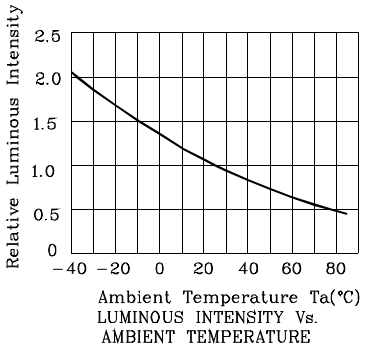


Note:the curves are on the segment b,c,e,f,g,h,j,l,m,n.



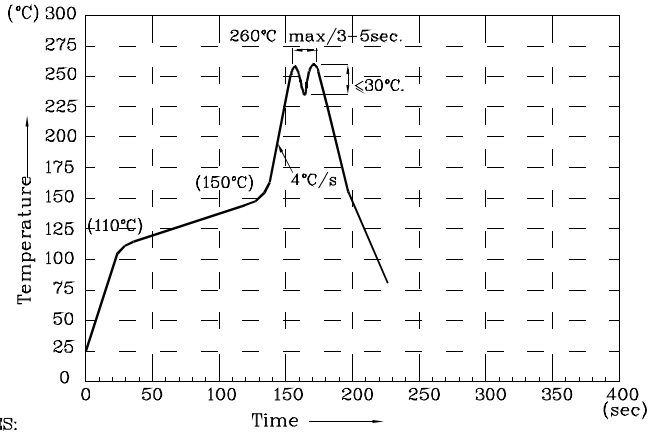






Note:the curves are on the DP.

Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



NOTES:

1. Recommend the wave temperature 245℃~260℃. The maximum soldering temperature should be less than 260℃.
2. Do not apply stress on epoxy resins when temperature is over 85℃.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. During wave soldering, the PCB top-surface temperature should be kept below 105℃.
5. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

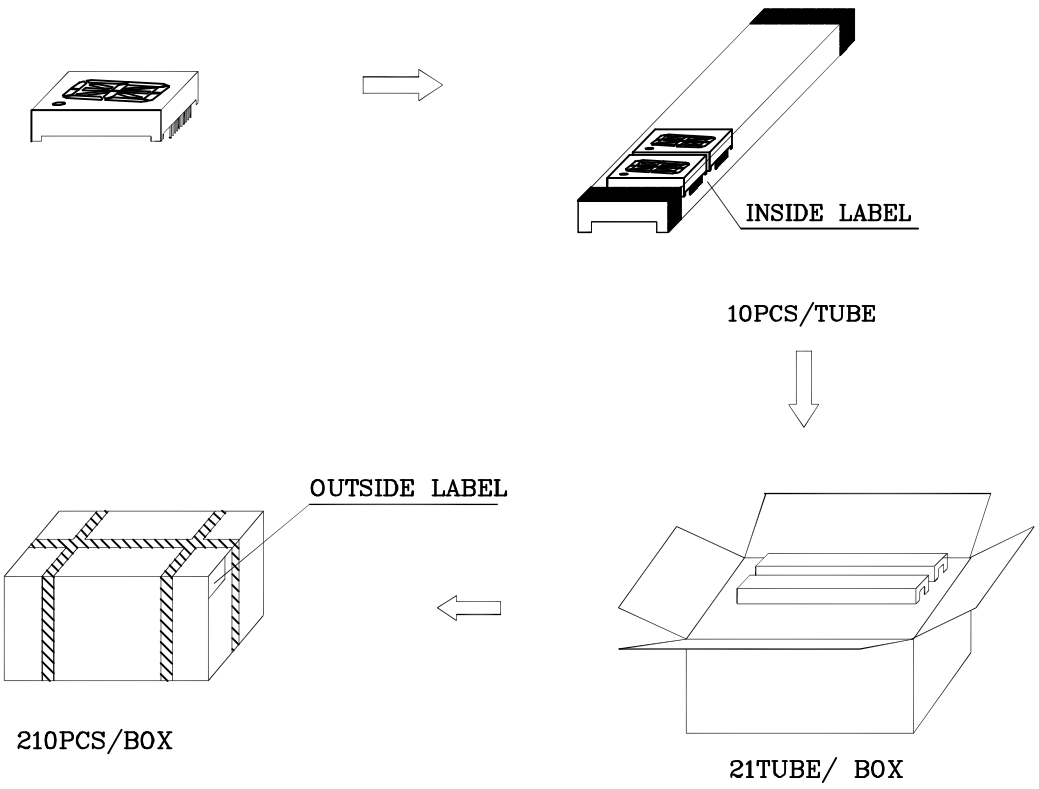
1. Wavelength: +/-1nm

2. Luminous Intensity / Luminous Flux: +/-15%

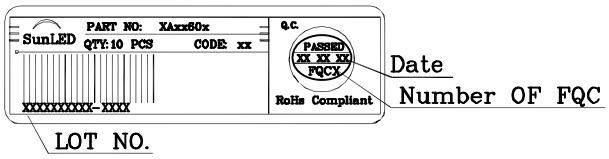
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box